

VERSION WITH MARKINGS TO SHOW CHANGES MADETITLE:

Specification at page 1, line 1:

~~MULTILAYER CERAMIC SUBSTRATE AND METHOD FOR~~  
~~FABRICATING THE SAME~~ METHOD FOR FABRICATING A MULTILAYER  
CERAMIC SUBSTRATE

SPECIFICATION:

Specification at page 1, line 5:

CROSS-RELATED APPLICATIONS

This application is a Divisional application of U.S. Patent Application  
Serial No. 09/173,288, filed October 14, 1998.

CLAIMS:

- 1           3. (As Amended) ~~The method for fabricating a multilayer ceramic substrate~~  
2 ~~recited in claim 1,~~ A method for fabricating a multilayer ceramic substrate  
3 comprising the steps of:
- 4           (a) manufacturing an intaglio plate of flexible resin substance, on which a  
5 first groove corresponding to a first conductive pattern is formed and a second  
6 groove having a depth deeper than that of the first groove is formed at a place  
7 corresponding to a via of the first conductive pattern;
- 8           (b) filling the first and the second grooves with an electroconductive paste;
- 9           (c) increasing conductivity of respective paths in said first and second  
10 grooves by deaerating and drying the paste;

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11 (d) adding additional electroconductive paste to said first and second  
12 grooves to replenish a decremented volume of said paste ;

13 (e) gluing said intaglio plate onto a ceramic substrate by applying heat and  
14 pressure;

15 (f) separating said intaglio plate from said ceramic substrate to have a  
16 pattern of the electroconductive paste transferred onto the ceramic substrate, and  
17 burning it so as to form said first conductive pattern on the ceramic substrate;

18 (g) forming an insulation layer on said first conductive pattern, wherein said  
19 insulation layer is formed by a printing technology covering the whole area of said  
20 first conductive pattern, and is dried, said via is exposed through abrasion or  
21 grinding of the dried ~~skin of said~~ insulation layer ~~before burning~~ and said insulation  
22 layer is burned after the exposure of said via;

23 (h) forming a second conductive pattern on said insulation layer.

Claims 1, 2, and 4-21 have been cancelled.

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